



**DEVETECH ELECTRONICS CO. LTD**

**CHIP VARISTOR 470V  
CUSTOMER: DACHS ELECTRONICA  
P/N: TMC R03-471K4032T**

DESIGNED BY	
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## 1 Electrical Characteristics

### 1.1 Technical Data

	Symbol	Value	Unit
Maximum allowable continuous AC voltage*1	VRMS	300.0	V
Maximum allowable continuous DC voltage	VDC	385.0	V
Varistor voltage Measured*2	VB	470(423-517)	V
Typical capacitance value measured*3	C	375	pF
Typical capacitance value tolerance		±30	%
Maximum clamping voltage measured*4	VC	775	V
Rated peak single pulse transient current at *5	I P	3500	A

### 1.2 Reference Data

	Symbol	Value	Unit
Maximum Energy Absorption 10/1000μs	E	98.0	J
Response time	T <sub>rise</sub>	<2	ns
Leakage current at V <sub>DC</sub> (At initial state)	I <sub>L</sub>	<50	μA
Leakage current at V <sub>DC</sub> (After reliability Test)	I <sub>LA</sub>	<100	μA
Operating ambient temperature		-45~+125	°C
Reflow temperature profile(Recommend)		260	°C

### 1.3 Other Data

Body	ZnO
End termination	Ag/Ni/Sn
Packaging	Bulk/Tape
Complies with Standard	IEC61000-4-5

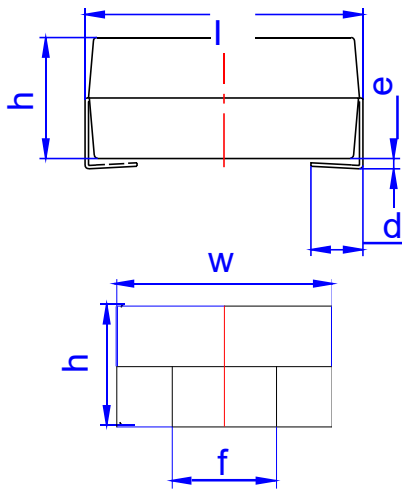
### 1.4 Notes:

*1 AC voltage at 50~60Hz	Measured at 1mA DC
*2 Varistor voltage	Measured at f=1MHz,Vrms=0.5V
*3 Capacitance	Measured at 10A by 8/20μs Pulse
*4 Maximum clamping voltage	Measured by 8/20μs Pulse
*5 Rated peak single pulse transient current	Measured at 1mA DC

### 1.5 Storage Condition

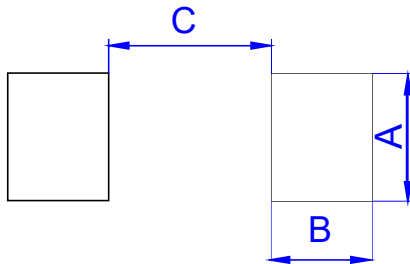
- As far as possible, the components should be employed within 24 months after delivery from Kangtai Semiconductor.
- They should be left in their original packing to avoid soldering problems due to oxidized contacts.
- Storage temperature: - 25 up to + 45°C.
- Relative humidity: < 75 % annual average, < 95 % on max. 30 days in a year.

## 2 Dimensional drawings



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
l	10.1		10.7	0.398		0.421
w	7.7		8.3	0.303		0.327
h	4.2		4.8	0.165		0.189
d	1.2		1.8	0.047		0.071
e	0		0.3	0		0.012
f	2.7		3.3	0.106		0.130

## 3 Recommended solder pad layout



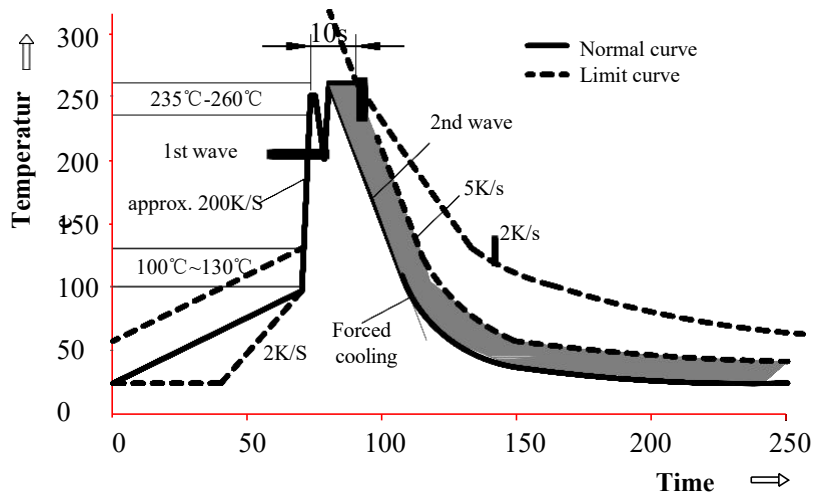
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A		3.5			0.138	
B		2.8			0.110	
C		6.5			0.265	

## 4 Soldering guidelines

The usage of mild, non-activated fluxes for soldering is recommended, as well as proper cleaning of the PCB.

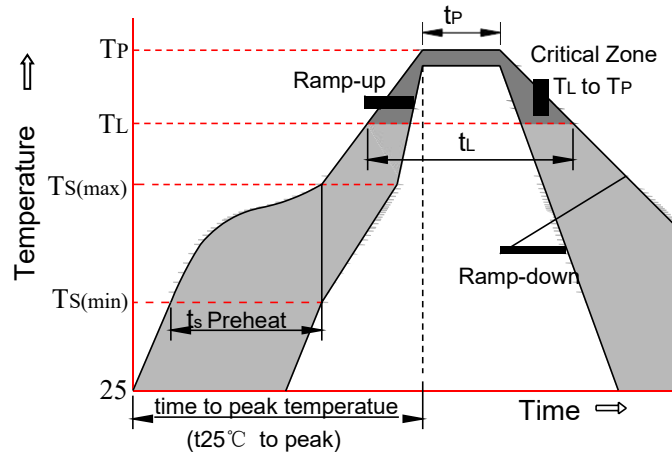
The components are suitable for reflow soldering per JEDEC J-STD-020C

### 4.1 Wave soldering



Temperature characteristics at component terminal with dual-wave soldering

## 4.2 Reflow soldering

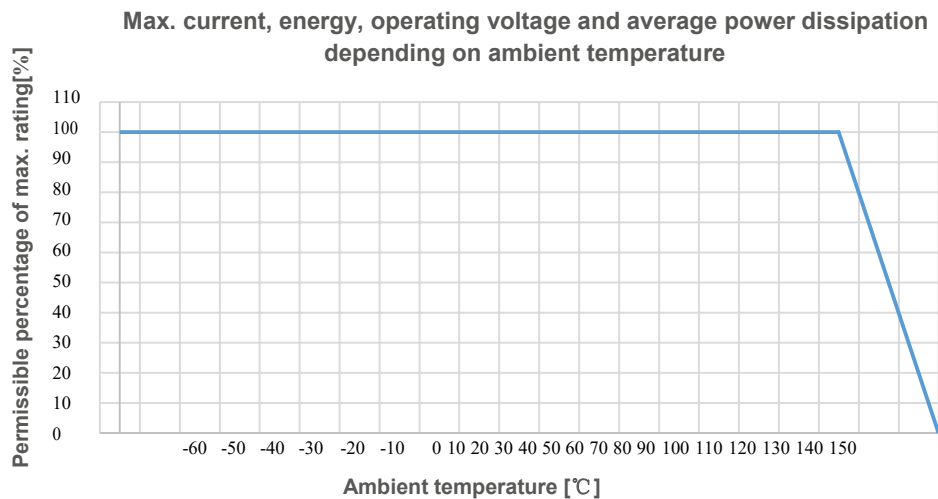


Profile feature		Sn-Pb assembly	Pb-Free assembly
Average ramp-up rate ( $T_{Smax}$ to $T_p$ )		3°C/sec. Max	3°C/sec. Max
Preheat	-Temperature min. ( $T_{s(min)}$ )	+100°C	+150°C
	-Temperature max. ( $T_{s(max)}$ )	+150°C	+200°C
	-Time ( $t_{Smin}$ to $t_{Smax}$ )	60-120 secs.	60-180 secs.
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max	3°C/sec. Max
Time maintained above	-Temperature min. ( $T_L$ )	+183°C	+217°C
	-Time ( $t_L$ )	60-150 secs.	60-150 secs.
Peak classification temperature ( $T_p$ )		+220°C to +240°C	+240°C to +260°C
Time within 5°C of actual peak temperature ( $t_p$ )		10 secs. to 30 secs.	20 secs. to 40 secs.
Ramp-down rate		6°C/sec. max.	6°C/sec. max.
Time 25°C to peak temperature		6 min. max.	8 min. max.

Notes: All temperature refer to topside of the package, measured on the package body surface

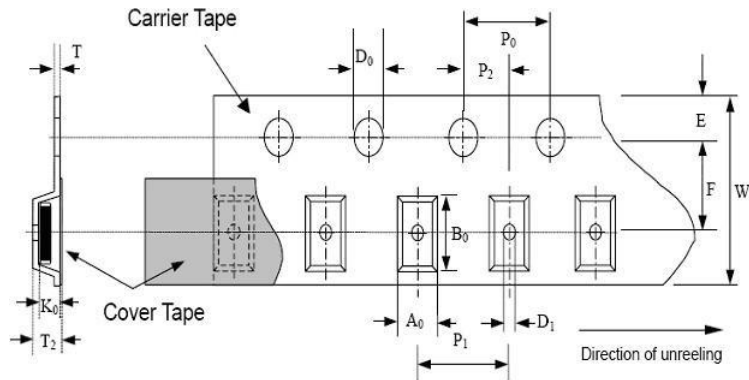
Maximum number of reflow cycles: 3

## 5 Temperature derating curve



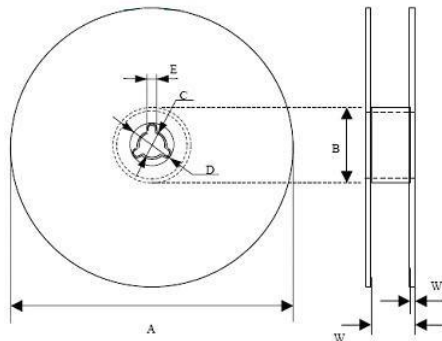
## 6 Taping and packaging Specification

### 6.1 Packaging Specification



type	A <sub>0</sub> ±0.20	B <sub>0</sub> ±0.20	K <sub>0</sub> ±0.10	T max	T <sub>2</sub> max	D <sub>0</sub> +0.05	D <sub>1</sub> ±0.05	P <sub>1</sub> ±0.10	P <sub>2</sub> ±0.05	P <sub>0</sub> ±0.1	W ±0.30	E ±0.10	F ±0.05
3220	7.0	8.7	—	0.3	5.50	1.55	1.55	12.00	2.00	4.00	16.00	1.75	7.50
4032	8.4	10.8	—	0.3	5.50	1.55	1.55	12.00	2.00	4.00	16.00	1.75	7.50

### 6.2 Reel dimension



type	A	B	C	D	E	W-W1	W <sub>1</sub>
3220-4032	329.0±1.0	60.0±0.5	13.0±0.2	21.0±0.2	2.0±0.5	17.2±0.7	2.3±0.15

1) Quantity of taping packing(pcs): 1000

## 7 Standards

### 7.1 UL (E487186)

Cot No>	Spd Tye	Volts (V)	AC/DC/ DC PV	PII	AMPS (A)	AMB (°C)min	AMB (°C)max	MODE	VPR (Vpk)	MLV (Vpk)	MCOV (V)	Vn (KA)	In (KA)	SCCR (KA)	NOTES
MVR3220-271H	5	175	AC	1	N/A	-40	85	Ld-Ld	-	640	175	270	0.5	N/A	1
MVR3220-471H	5	300	AC	1	N/A	-40	85	Ld-Ld	-	850	300	470	0.5	N/A	1

### 7.2 TUV



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## NOTES

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